

N-Channel Reduced Q_g , Fast Switching MOSFET

PRODUCT SUMMARY		
V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A)
20	0.0028 at $V_{GS} = 10$ V	25
	0.0040 at $V_{GS} = 4.5$ V	22

FEATURES

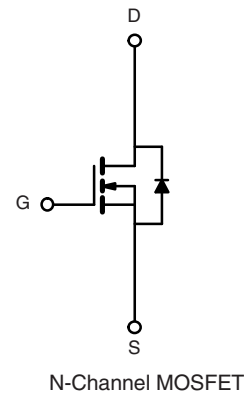
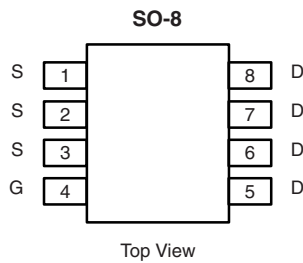
- Halogen-free According to IEC 61249-2-21 Definition
- Extremely Low Q_{gd} for Switching Losses
- Ultra-Low On-Resistance
- 100 % R_g and UIS Tested
- Compliant to RoHS Directive 2002/95/EC



RoHS
COMPLIANT
HALOGEN
FREE
Available

APPLICATIONS

- Synchronous Rectifier in Low Power DC/DC Converters
- POL
- OR-ing



Ordering Information: Si4398DY-T1-E3 (Lead (Pb)-free)
Si4398DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C, unless otherwise noted)					
Parameter	Symbol	10 s	Steady State	Unit	
Drain-Source Voltage	V_{DS}	20		V	
Gate-Source Voltage	V_{GS}	± 20			
Continuous Drain Current ($T_J = 150$ °C) ^a	I_D	$T_A = 25$ °C	25	19	A
		$T_A = 70$ °C	20	13	
Pulsed Drain Current (10 μ s Pulse Width)	I_{DM}	70			
Continuous Source Current (Diode Conduction) ^a	I_S	2.9	1.3		
Avalanche Current	I_{AS}	40		mJ	
Single Pulse Avalanche Energy		E_{AS}	80		
Maximum Power Dissipation ^a	P_D	$T_A = 25$ °C	3.5	1.6	W
		$T_A = 70$ °C	2.2	1.0	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to 150		°C	

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^a	R_{thJA}	$t \leq 10$ s	29	35	°C/W
		Steady State	67	80	
Maximum Junction-to-Foot (Drain)	R_{thJF}	13	16		

Notes:

a. Surface mounted on 1" x 1" FR4 board.

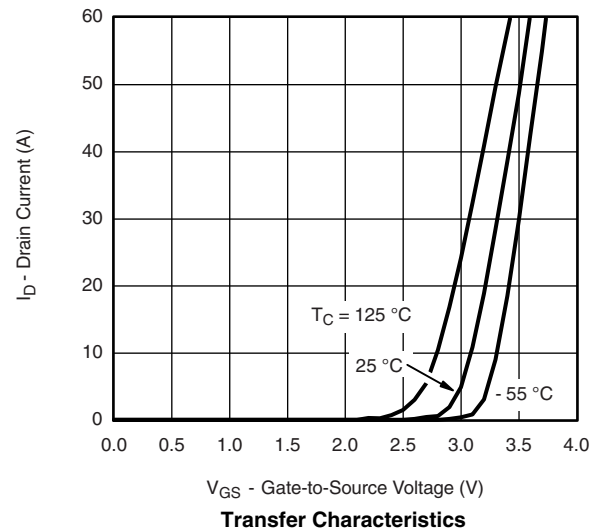
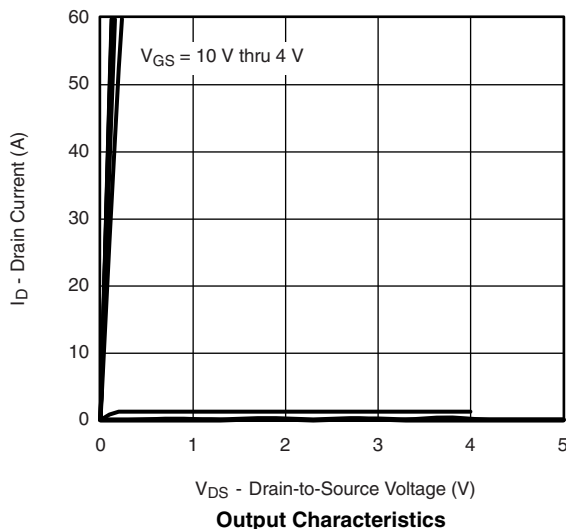
SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	1.0		3.0	V
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 12 V			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 20 V, V _{GS} = 0 V			1	μA
		V _{DS} = 20 V, V _{GS} = 0 V, T _J = 55 °C			5	
On-State Drain Current ^a	I _{D(on)}	V _{DS} ≥ 5 V, V _{GS} = 10 V	50			A
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 25 A		0.0023	0.0028	Ω
		V _{GS} = 4.5 V, I _D = 22 A		0.0033	0.0040	
Forward Transconductance ^a	g _{fs}	V _{DS} = 10 V, I _D = 15 A		95		S
Diode Forward Voltage ^a	V _{SD}	I _S = 2.9 A, V _{GS} = 0 V		0.72	1.1	V
Dynamic^b						
Input Capacitance	C _{iss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		5620		pF
Output Capacitance	C _{oss}			1340		
Reverse Transfer Capacitance	C _{rss}			540		
Total Gate Charge	Q _g	V _{DS} = 10 V, V _{GS} = 4.5 V, I _D = 20 A		34	50	nC
Gate-Source Charge	Q _{gs}			17.5		
Gate-Drain Charge	Q _{gd}			7.5		
Gate Resistance	R _g		0.7	1.4	2.1	Ω
Turn-On Delay Time	t _{d(on)}	V _{DD} = 10 V, R _L = 10 Ω I _D ≅ 1 A, V _{GEN} = 4.5 V, R _g = 6 Ω		23	35	ns
Rise Time	t _r			15	23	
Turn-Off Delay Time	t _{d(off)}			80	120	
Fall Time	t _f			23	35	
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 2.9 A, di/dt = 100 A/μs		50	80	

Notes:

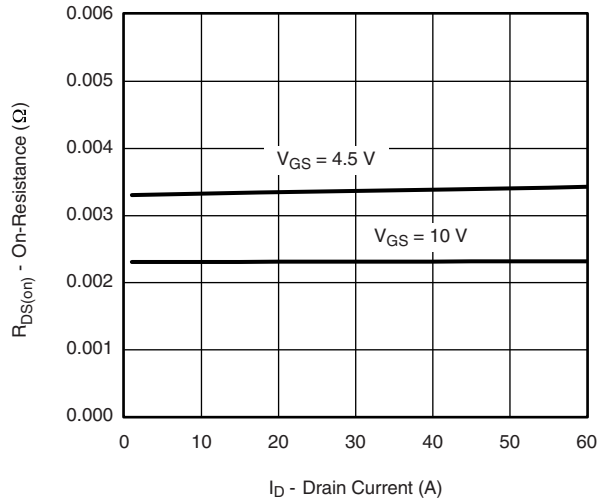
- a. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2 %.
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

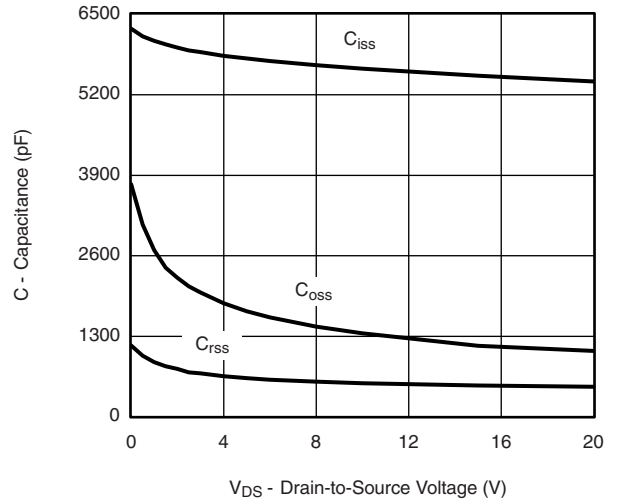
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



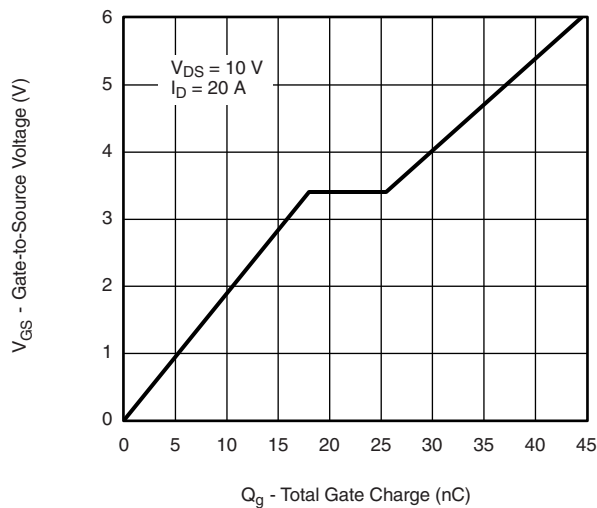
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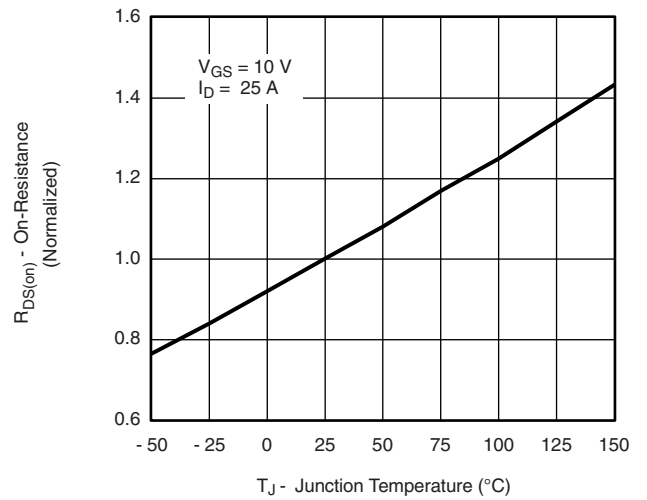
On-Resistance vs. Drain Current



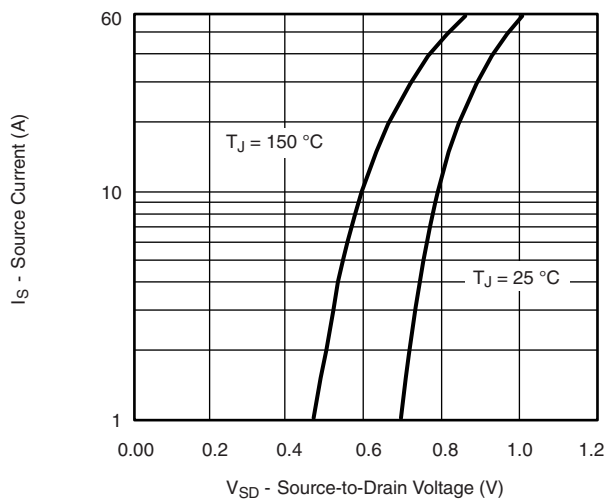
Capacitance



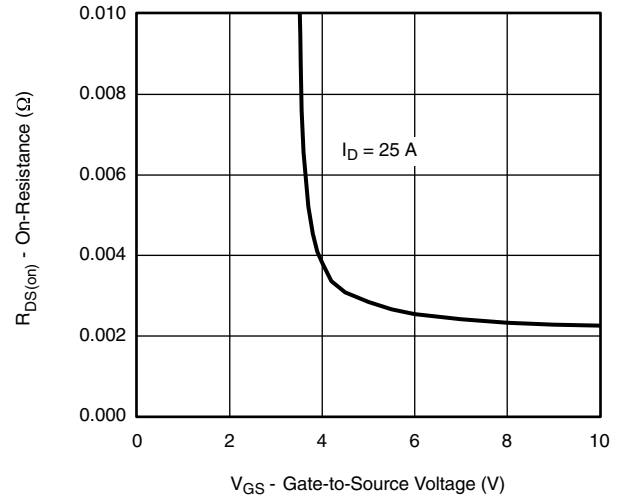
Gate Charge



On-Resistance vs. Junction Temperature

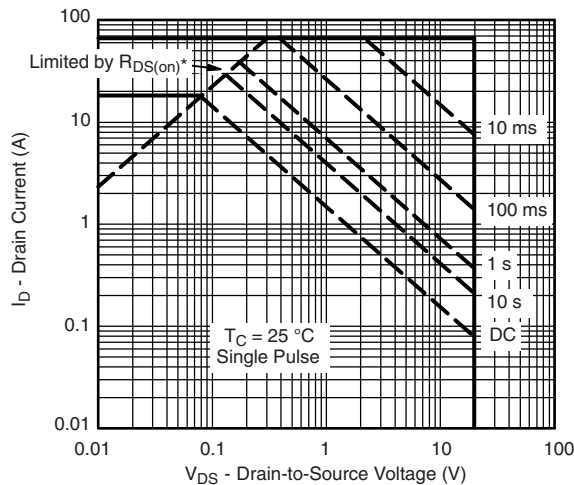
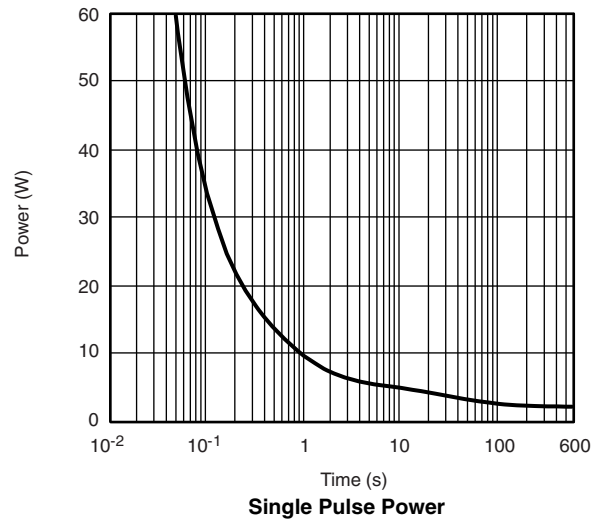
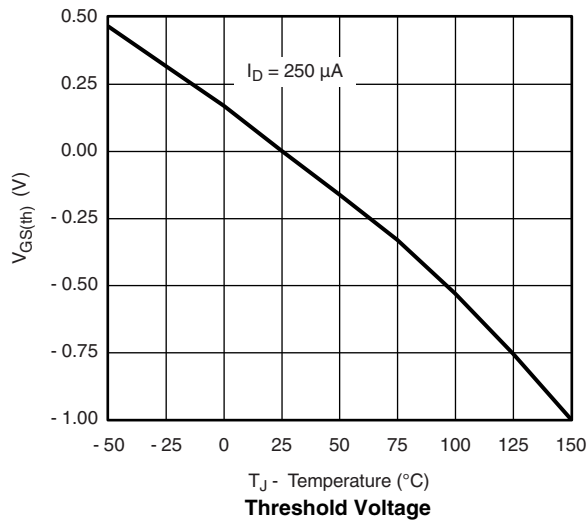


Source-Drain Diode Forward Voltage

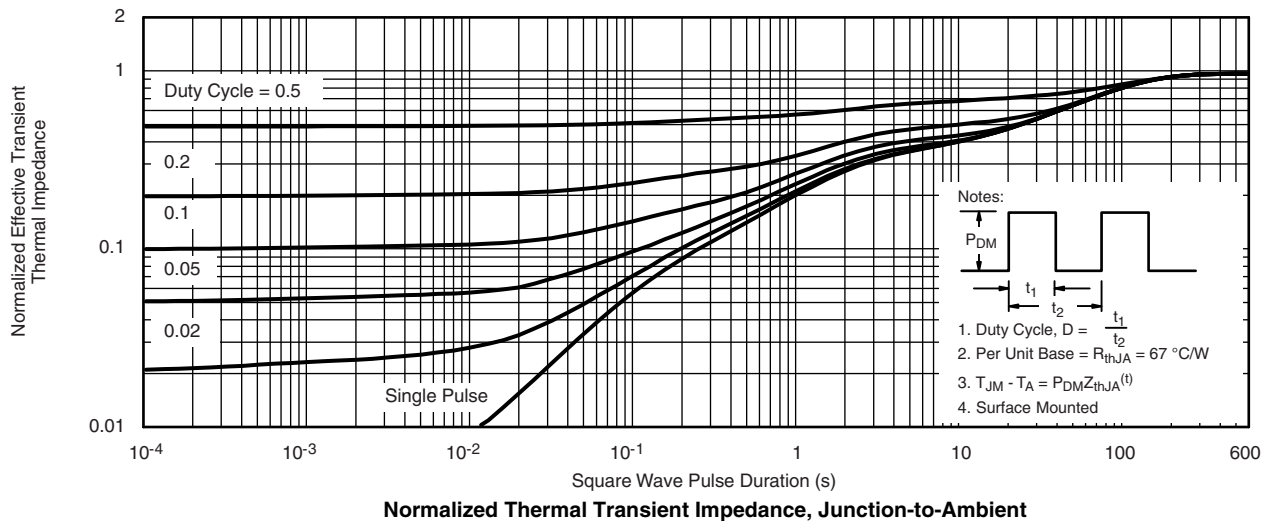


On-Resistance vs. Gate-to-Source Voltage

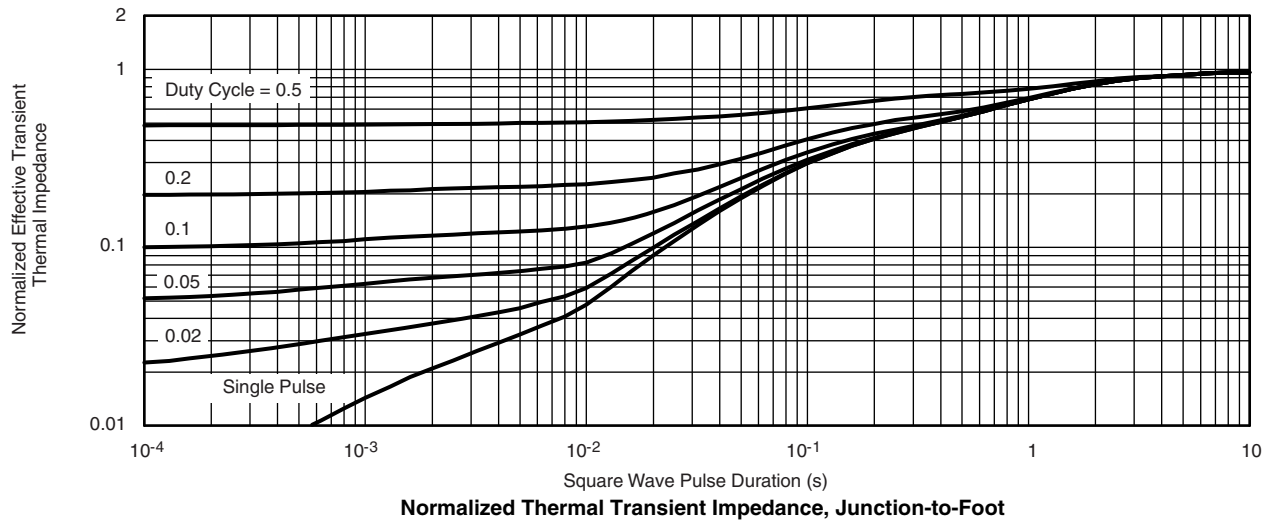
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified
Safe Operating Area, Junction-to-Case



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



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